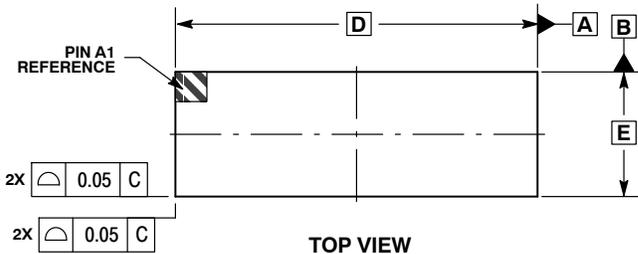




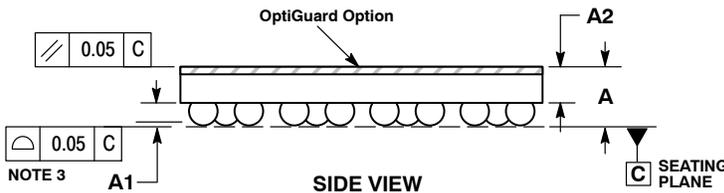
SCALE 4:1

WLCSP20, 4.01x1.38
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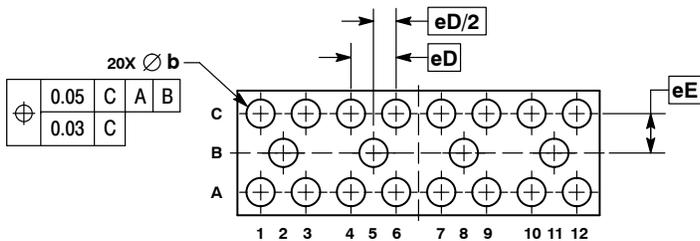
DATE 26 JUL 2010



TOP VIEW

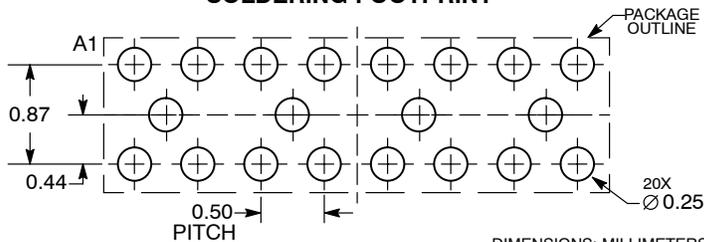


SIDE VIEW



BOTTOM VIEW

RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42 REF	
b	0.29	0.35
D	4.01 BSC	
E	1.38 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

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DESCRIPTION:	WLCSP20, 4.01X1.38	PAGE 1 OF 1

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